

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT						
NATURE OF CONVEYANCE:	ASSIGNMENT						
CONVEYING PARTY DATA							
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:70%;">Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Cheng-Ming Lin</td> <td>12/26/2006</td> </tr> <tr> <td>Chai-Wei Chang</td> <td>12/28/2006</td> </tr> </tbody> </table>		Name	Execution Date	Cheng-Ming Lin	12/26/2006	Chai-Wei Chang	12/28/2006
Name	Execution Date						
Cheng-Ming Lin	12/26/2006						
Chai-Wei Chang	12/28/2006						
RECEIVING PARTY DATA							
Name:	Taiwan Semiconductor Manufacturing Company, Ltd.						
Street Address:	No. 8, Li-Hsin, Rd. 6, Science-Based Industrial Park						
City:	Hsin-Chu						
State/Country:	TAIWAN						
Postal Code:	300-77						
PROPERTY NUMBERS Total: 1							
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:30%;">Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>11686238</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	11686238		
Property Type	Number						
Application Number:	11686238						
CORRESPONDENCE DATA							
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<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>							
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ATTORNEY DOCKET NUMBER:	2006-0614 / 24061.845						
NAME OF SUBMITTER:	David M. O'Dell						
Total Attachments: 2 source=Assignment#page1.tif source=Assignment#page2.tif							

CH \$40.00 11686238

ASSIGNMENT

WHEREAS, we,

- (1) Cheng-Ming LIN of No. 177-1, Anding Village, Siluo Township
Yunlin County 648, Taiwan R.O.C.
- (2) Chai-Wei CHANG of 5F., No. 30, Lane 506, Wusing St., Sinyi District
Taipei City 110, Taiwan, R.O.C.

have invented certain improvements in

**METHOD AND SYSTEM FOR REDUCING
CRITICAL DIMENSION SIDE-TO-SIDE TILTING ERROR**

for which we have executed an application for Letters Patent of the United States of America,

 of even date filed herewith; and
 X filed on March 14, 2007 and assigned application number 11/686,238; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for One Dollar (\$1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal,

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Customer No.: 42717

substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Cheng-Ming LIN

Residence Address: No. 177-1, Anding Village, Siluo Township
Yunlin County 648, Taiwan R.O.C.

Dated: Dec. 26th' 2006

Cheng-ming LIN
Inventor Signature

Inventor Name: Chai-Wei CHANG

Residence Address: 5F., No.30, Lane 506, Wusing St., Sinyi District,
Taipei City 110, Taiwan (R.O.C.)

Dated: Dec. 28th' 2006

Chia-Wei Chang
Inventor Signature